This summary aims to give you an overview of the information contained in this document. As it is a summary, it does not contain all the information that may be important to you. You should read this document in its entirety before you decide to **[REDACTED]** *in the* **[REDACTED]**. *There are risks associated with any* **[REDACTED]**. *Some of the particular risks in* **[REDACTED]** *in the* **[REDACTED]** *are set forth in the section headed "Risk Factors" in this document. You should read that section carefully before you decide to* **[REDACTED]** *in the* **[REDACTED]**.

OVERVIEW

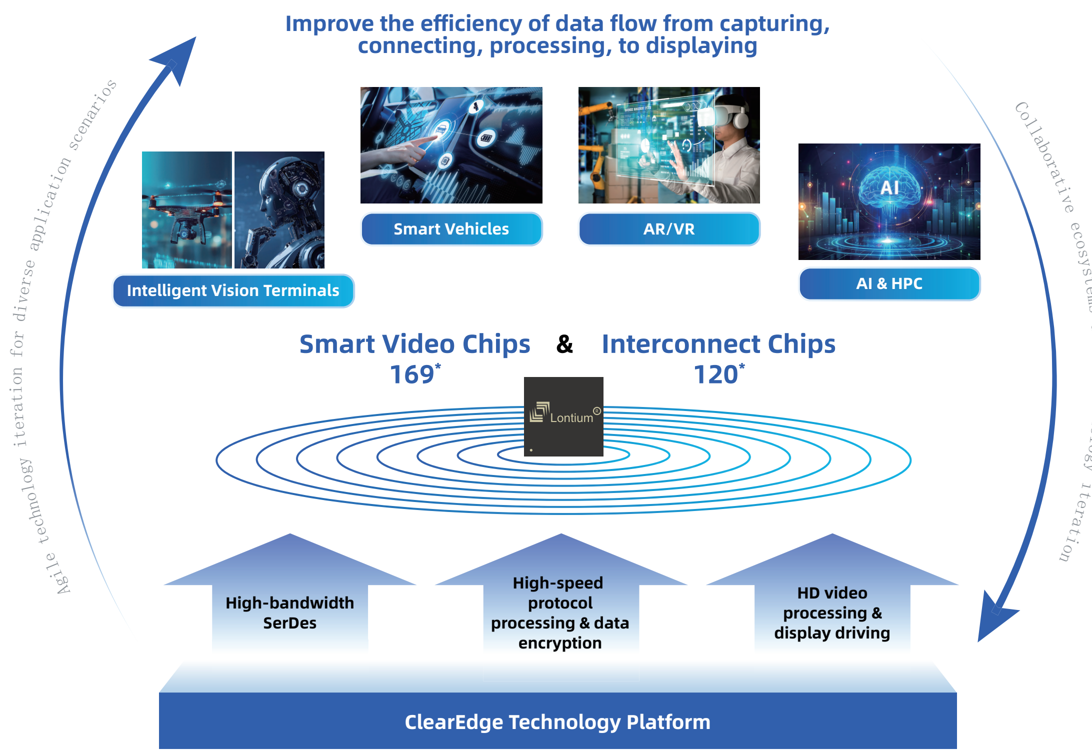
Who We Are

We are a recognized fabless high-speed mixed-signal chip design company dedicated to upgrading data transmission and video processing infrastructure for smart terminals and devices, as well as AI applications. Our addressable market primarily comprises two segments: interconnect chips and smart video chips. Leveraging our three foundational technology pillars, including (i) high-bandwidth Serializer/Deserializer ("**SerDes**"), (ii) high-speed interface protocol processing and data encryption, and (iii) high-definition ("**HD**") video and audio processing and display driver technologies, our products facilitate efficient data processing, transmission, and format conversion among computing, storage, and display units. Key applications include intelligent vision terminals, smart vehicles, AR/VR devices and AI & high-performance computing ("**HPC**"). Our chips integrate high-definition video processing and display capabilities with intelligent sensing and human-machine interaction technologies, establishing a solid technical foundation designed to support future on-device AI-powered applications. According to Frost & Sullivan, we are the number one fabless design company based in Chinese Mainland in the video bridging chip market in terms of revenue in 2025, with a market share of 4.1%, which represents a key segment of mixed-signal chips.

HD audio and video data serve as a vital bridge between the physical and digital worlds. The high-speed, and stable transmission of such data among robotics and drones, AR/VR devices, autonomous driving systems, and high-performance computing systems, relies on the three foundational technology pillars. Our nearly two decades of research and development ("**R&D**") investment in these core technologies underpin the intelligent vision era. Leveraging our high-bandwidth SerDes technology, we have expanded into the broader domain of interconnect chips, including critical interconnect components such as PCIe/CXL/USB retimers and switches. These products address multimodal data transmission bottlenecks in complex HPC and AI environments, including scale-up (intra-GPU cluster), scale-out (data center), and scale-across (inter-data center) architectures.

Our Products and Solutions

Our chips serve key application scenarios, including: (i) intelligent vision terminals, (ii) smart vehicles, (iii) AR/VR, and (iv) AI & HPC. We offer end-to-end solutions encompassing capturing, connecting, processing, and displaying capabilities. Our product offerings, comprising 169 smart video chips and 120 interconnect chips as of December 31, 2025, enable data flow across heterogeneous systems. We cultivate a synergistic ecosystem where user application feedback and strategic partnerships, including reference design collaborations with global semiconductor leaders, fuel continuous technological iteration and solution enhancement. The following diagram illustrates our underlying technologies, product matrix and application scenarios:



Note: As of December 31, 2025

- **Intelligent Vision Terminals:** Our chips enable the lossless transmission of visual details and are widely deployed in drones, robotics, smart commercial displays and smart video conferencing systems. In 2025, 76.1% of our total revenue were generated from this application, and from 2023 to 2025, our revenue for this application grew at a CAGR of 27.7%.

- **Smart Vehicles:** We span both the cockpit and driving domains, enabling multi-system, multi-screen interconnectivity by transmitting large volumes of sensor data from cameras, LiDAR and millimeter-wave radar to domain controllers, and to displays with high speed and stability. As of December 31, 2025, we had developed 19 automotive-grade chips that had passed AEC-Q100 certification, and our products and solutions had been adopted by original equipment manufacturers ("**OEMs**") and tier-1 suppliers serving leading European, U.S. and Chinese automotive brands. In 2025, 15.7% of our total revenue were generated from this application, and from 2023 to 2025, our revenue from this application grew at a CAGR of 59.6%.

- **AR/VR:** Our chips support high-resolution (up to binocular 8K) and high-refresh-rate (up to 120 Hz) display performance with ultra-low latency for AR/VR devices. Through development collaboration with leading SoC vendors such as Qualcomm and panel manufacturers such as Sony, we are building a "SoC + Chip + Panel" ecosystem and have become a key partner in Sony's AR display panel reference design. Our chips have been adopted by global AR/VR brands such as RayNeo, Rokid, XREAL and a global market leader in consumer MR headsets based in the U.S. In 2025, 6.4% of our total revenue were generated from this application, and from 2023 to 2025, our revenue for this application grew at a CAGR of 27.6%.

- **AI & HPC:** We are expanding into the AI & HPC sectors and developing high-speed signal conversion and interconnect solutions to meet the demanding requirements of next-generation computing systems. In 2025, 1.8% of our total revenue were generated from this application.

In recent years, the global semiconductor chip market has continued to expand, driven by rising demand for high-performance electronic systems in various applications. According to Frost & Sullivan, within the overall semiconductor chip industry, smart video chips and interconnect chips are two important segments that perform fundamental functions in modern electronic systems. Smart video chips are key semiconductor components in display devices, enabling the processing, conversion and transmission of video signals to support image presentation and enhance visual performance. Interconnect chips serve as the data-movement enabler of electronic systems, allowing high-speed and reliable data transmission among processors, memory, storage and other systems components. In terms of market size by revenue, the smart video chip and interconnect chip markets accounted for 2.2% and 3.2% of the overall semiconductor chip industry, respectively, in 2025. The market sizes of the smart video chips and interconnect chips are expected to reach RMB143.1 billion and RMB490.7 billion by 2030, respectively, representing a CAGR of 6.4% and 23.1%, respectively. Moreover, the video bridging chip market is the fastest growing sub-segment within the smart video chip market. In 2025, the video bridging chip market accounted for 10.4% of the smart video chip market and is expected to reach RMB22.1 billion of global market size by 2030, at a CAGR of 15.3%. With our strong brand influence, market leadership position, comprehensive product coverage and proven technological innovation capabilities, we believe we are well-positioned to capture the growth opportunities in our addressable markets and further strengthen our industry leadership.

OUR COMPETITIVE STRENGTHS

We believe the following competitive strengths have contributed to our success and will continue to drive our future growth: (i) recognized high-speed mixed-signal chip design company; (ii) proprietary, in-house developed underlying technology platform; (iii) product portfolio targeting high-growth application scenarios; (iv) widespread operations and close collaboration with industry ecosystem leaders; and (v) visionary and experienced management team.

OUR GROWTH STRATEGIES

We will pursue the following strategies to drive further growth: (i) strengthening R&D investment to support continued core technology and product development; (ii) targeting high-value and high-volume application scenarios to continuously enrich our product matrix and reach higher revenue growth rate; (iii) expanding market presence and establishing a scalable operational system; (iv) strengthening talent development to empower R&D and growth; and (v) exploring strategic investment and M&A opportunities.

OUR PRODUCTS

To meeting the increasing demand for ultra-low latency, ultra-high bandwidth, and high reliability data transmission, as well as intelligent interaction in the intelligent vision era, we offer a product portfolio of smart video chips and interconnect chips that delivers end-to-end solutions covering capturing, connecting, processing, and displaying capabilities. With a portfolio of 169 smart video chips and 120 interconnect chips as of December 31, 2025, we produce mixed-signal products that bridge the physical and digital worlds through robust connectivity.

The following table sets forth our revenue generated during the Track Record Period in terms of the products we offered:

	Year Ended December 31,					
	2023		2024		2025	
	RMB	*%*	*RMB*	*%*	*RMB*	*%*
			(in thousands, except percentages)			
Smart video chips	269,543	83.4	381,387	81.8	473,109	83.3
Interconnect chips	52,154	16.1	73,287	15.7	93,331	16.4
Others[(1)]	1,450	0.5	11,329	2.5	1,764	0.3
Total	**323,147**	**100.0**	**466,003**	**100.0**	**568,204**	**100.0**

Note:

(1) "Others" primarily include revenue from technological services and ancillary components. Technological services include technology licensing and custom chip design services. Ancillary components include printed circuit boards, security keys and other auxiliary chips.

OUR SALES NETWORK

Our products are standardized and serve a wide range of downstream applications. Our customer base is relatively dispersed, and most of our end customers purchase a variety of chips, preferring to procure through distributors. As a result, our sales model is primarily distributor-based, supplemented by direct sales. Distributors purchase our products, taking title and risk upon delivery, and resell them at their own prices, with reference to our recommended guidance. During the Track Record Period, substantially all of our revenue was generated from our distributors.

The table below sets forth a breakdown of revenue contribution by sales channels for the periods indicated.

	Year Ended December 31,					
	2023		2024		2025	
	RMB	*%*	*RMB*	*%*	*RMB*	*%*
			(in thousands, except percentages)			
Distributors	319,481	98.9	459,835	98.7	561,284	98.8
Direct sales	3,666	1.1	6,168	1.3	6,920	1.2
Total	**323,147**	**100.0**	**466,003**	**100.0**	**568,204**	**100.0**

OUR FABLESS BUSINESS MODEL

Since our inception, we have operated under a fabless model, primarily focusing on the research and development and sales of integrated circuits. After completing chip design, we outsource wafer fabrication to independent foundries and assembly and testing services to third-party providers. By concentrating our resources on product R&D, we are able to respond swiftly to changing market demands and continuously drive product innovation, while leveraging our manufacturing partners' relatively advanced processes and economies of scale. For details, see "Business — Our Fabless Business Model."

OUR CUSTOMERS AND SUPPLIERS

During the Track Record Period, our customers primarily consisted of distributors. Our five largest customers in each of 2023, 2024 and 2025 together accounted for 49.4%, 51.6% and 52.3% of our total revenue, respectively. Revenue from our largest customer in each of 2023, 2024 and 2025 accounted for 16.4%, 13.9% and 17.2% of our total revenue, respectively.

During the Track Record Period, our suppliers primarily consisted of (i) wafer foundries, and (ii) companies that provide services in assembly and testing. Purchases from our five largest suppliers in each of 2023, 2024 and 2025 accounted for 83.2%, 93.1% and 90.6% of our total purchases, respectively. In addition, purchases from our largest supplier in each of 2023, 2024 and 2025 accounted for 34.3%, 41.1% and 39.0% of our total purchases, respectively.

COMPETITION

We operate in a highly competitive and concentrated industry, with increasing demand for innovative and efficient products. Our competition primarily revolves around product performance, technical innovation, cost-efficiency, and market responsiveness. We compete with both foreign and domestic companies focusing on chips with strong performance in ultra-high-definition ("**UHD**") video processing, multi-protocol compatibility, and low-latency interconnect. According to Frost & Sullivan, foreign companies hold a large market share of the global market. However, in recent years, companies based in Chinese Mainland have achieved rapid growth and increased their market shares by leveraging their technological innovation capabilities. According to Frost & Sullivan, we are the number one fabless design company based in Chinese Mainland in the video bridging chip market in terms of revenue in 2025 with a market share of 4.1%. We remain focused on leveraging our technological expertise, customer-centric solutions, and operational efficiency to maintain and enhance our position in the market.

SUMMARY OF CONSOLIDATED HISTORICAL FINANCIAL INFORMATION

Key Items of Consolidated Statements of Profit or Loss

The following table sets forth a summary of our consolidated statements of profit or loss for the periods indicated.

	Year Ended December 31,					
	2023		2024		2025	
	RMB'000	*%*	*RMB'000*	*%*	*RMB*	*%*
Revenue	**323,147**	**100.0**	**466,003**	**100.0**	**568,204**	**100.0**
Cost of sales	(149,876)	(46.4)	(213,149)	(45.7)	(267,532)	(47.1)
Gross profit	**173,271**	**53.6**	**252,854**	**54.3**	**300,672**	**52,9**
Other income and gains, net	44,044	13.6	43,552	9.3	37,138	6.5
Selling and marketing expenses	(9,090)	(2.8)	(11,072)	(2.4)	(10,274)	(1.8)
Administrative expenses	(27,273)	(8.4)	(28,620)	(6.1)	(35,309)	(6.2)
Research and development expenses	(74,527)	(23.1)	(99,969)	(21.5)	113,248	(19,9)
Impairment losses on financial assets under the ECL model, net	(139)	(0.0)	(1,490)	(0.3)	(2,217)	(0.4)
Other expenses	(1,006)	(0.3)	(2,270)	(0.5)	(2,075)	(0.4)
Finance costs	(63)	(0.0)	(37)	(0.0)	(12)	(0.0)
Profit before tax	**105,217**	**32.6**	**152,948**	**32.8**	**174,675**	**30.7**
Income tax expense	(2,521)	(0.8)	(8,536)	(1.8)	(2,758)	(0.5)
Profit for the year	**102,696**	**31.8**	**144,412**	**31.0**	**171,917**	30.3

Cost of Sales

The following table sets forth a breakdown of our cost of sales, in absolute amounts and as percentages of our total cost of sales for the periods indicated.

	Year Ended December 31,					
	2023		2024		2025	
	RMB'000	*%*	*RMB'000*	*%*	*RMB'000*	*%*
Cost of wafers	103,637	69.1	145,934	68.5	176,120	65.8
Cost of assembly and testing	40,028	26.7	56,400	26.5	77,418	28.9
Other cost of sales	6,226	4.2	7,888	3.7	9,597	3.6
Impairment	(15)[1]	(0.0)	2,927	1.3	4,397	1.6
Total	**149,876**	**100.0**	**213,149**	**100.0**	**267,532**	**100.0**

Note:

(1) We recorded reversal of impairment in 2023, mainly attributable to the decreased ending balance of inventories as of December 31, 2023, mainly due to our increased sales and recovery of the industry.

Our cost of sales maintained an upward trend during the Track Record Period, primarily due to the increases in cost of wafers and cost of assembly and testing, resulting from our increased product sales and business expansion.

Summary of Consolidated Statements of Financial Position

The following table sets forth selected information from our consolidated statements of financial position as of the dates indicated.

	As of December 31,		
	2023	2024	2025
	RMB'000	*RMB'000*	*RMB'000*
Total non-current assets	113,168	124,342	180,839
Total current assets	1,373,369	1,378,018	1,477,171
Total assets	**1,486,537**	**1,502,360**	**1,658,010**
Total non-current liabilities	10,662	13,987	10,754
Total current liabilities	46,409	56,573	87,766
Total liabilities	**57,071**	**70,560**	**98,520**
Net current assets	1,326,960	1,321,445	1,389,405
Total equity	**1,429,466**	**1,431,800**	**1,559,490**

Our total equity increased from RMB316.2 million as of January 1, 2023 to RMB1,429.5 million as of December 31, 2023, primarily driven by the net proceeds of RMB1,030.3 million raised from our listing on the Shanghai Stock Exchange in 2023, as well as profit for the year of RMB102.7 million, partially offset by dividends declared of RMB20.8 million. Our total equity remained relatively stable at RMB1,431.8 million as of December 31, 2024, compared to RMB1,429.5 million as of December 31, 2023. Profit for the year of RMB144.4 million was substantially offset by shares repurchased of RMB59.2 million and dividends declared of RMB96.5 million, partially countered by share-based payment expenses of RMB12.1 million and related tax implications of RMB1.5 million. Our total equity increased to RMB1,559.5 million as of December 31, 2025, primarily due to our profit for the year of RMB171.9 million, partially offset by dividends declared of RMB71.0 million.

See "Appendix I — Consolidated Statements of Changes in Equity" for more details.

Our net current assets remained relatively stable at RMB1,327.0 million and RMB1,321.4 million as of December 31, 2023 and 2024, respectively. Our net current assets subsequently increased to RMB1,389.4 million as of December 31, 2025, primarily due to an increase in cash and cash equivalents of RMB97.4 million generated from our business operations.

See "Financial Information — Selected Balance Sheet Items" for more details.

Summary of Consolidated Statements of Cash Flows

The following table sets forth selected information from our consolidated cash flows for the periods indicated.

	Year Ended December 31,		
	2023	2024	2025
	RMB'000	*RMB'000*	*RMB'000*
Net cash flows from operating activities	103,412	116,887	112,413
Net cash flows (used in)/from investing activities	(1,063,108)	286,415	43,731
Net cash flows from/(used in) financing activities	1,008,945	(155,823)	(57,838)
Cash and cash equivalents at the beginning of the year	62,805	112,332	359,922
Cash and cash equivalents at the end of the year	112,332	359,922	457,279

See "Financial Information — Liquidity and Capital Resources — Cash Flows Analysis".

KEY FINANCIAL RATIOS

The following table sets out our key financial ratios for the periods indicated.

	As of/For the year ended December 31,		
	2023	2024	2025
Revenue growth rate	34.1%	44.2%	21.9%
Quick ratio	28.0	22.3	15.0
Return on assets	11.1%	9.7%	10.9%
Return on equity	11.8%	10.1%	11.5%
Gross profit margin	53.6%	54.3%	52.9%
Net profit margin	31.8%	31.0%	30.3%

See "Financial Information — Key Financial Ratios" for more details.

RISK FACTORS

Our operations involve certain risks and uncertainties. The more significant risks relating to our business and industry include: (i) the industries in which we operate are highly competitive. If we fail to compete against other market players, our business, results of operations and financial condition may be materially and adversely affected; (ii) our inability to continuously advance our technological and R&D capabilities could render our products uncompetitive and obsolete; (iii) our success depends on our ability to protect and enforce our intellectual property rights and to maintain freedom to operate in all jurisdictions where we conduct business; (iv) we partner with third-party wafer foundries and assembly and testing service providers. We are exposed to supplier concentration risk due to our reliance on such major suppliers; and (v) any decrease in sales from, or loss of, one or more of our major customers would have negative impacts on our results of operations.

LEGAL PROCEEDINGS AND COMPLIANCE

During the Track Record Period and up to the Latest Practicable Date, we had not been and were not a party to any legal, arbitral or administrative proceedings that would have a material adverse effect on our business, financial conditions and operations, and we were not aware of any pending or threatened legal, arbitral or administrative proceedings against us or our Directors that could, individually or in the aggregate, have a material adverse effect on our business, financial condition and results of operations. During the Track Record Period and up to the Latest Practicable Date, we had complied with all relevant laws and regulations applicable to us in all material respects concerning our operations, and as advised by our PRC Legal Adviser, we had not been subject to any administrative penalties imposed by relevant regulatory authorities for material breaches of applicable laws and regulations. See "Business — Legal Proceedings and Compliance" for more details.

OUR CONTROLLING SHAREHOLDERS

As of the Latest Practicable Date, our Company was held as to (i) 37.67% by Mr. Chen (excluding Treasury Shares) and (ii) 3.32% by Xincaifu (excluding Treasury Shares), which was ultimately controlled by Mr. Chen as its sole executive partner who was entitled to exercise all voting rights of the Shares held by Xincaifu. Pursuant to the voting rights entrustment agreement, the voting rights attached to the Shares held by Ms. Qiu have been irrevocably entrusted to Mr. Chen, representing 3.46% voting rights (excluding Treasury Shares) in our Company as of the Latest Practicable Date. Therefore, as of the Latest Practicable Date, Mr. Chen was entitled to exercise a total of 44.45% of the voting power at general meetings (excluding Treasury Shares) of our Company.

Accordingly, immediately following the completion of the **[REDACTED]** (assuming the **[REDACTED]** is not exercised and no additional Shares are issued pursuant to our Restrictive Shares Incentive Plan), Mr. Chen will be entitled to exercise a total of **[REDACTED]**% of the voting power at general meetings (excluding Treasury Shares) of our Company. Upon **[REDACTED]**, Mr. Chen and Xincaifu will together constitute a group of our Controlling Shareholders under the Listing Rules. For further details of our corporate structure and the shareholding of our Controlling Shareholders, see "History and Corporate Structure — Corporate Structure" and "Relationship with Our Controlling Shareholders" in this document.

OUR LISTING ON THE SHANGHAI STOCK EXCHANGE

Since February 2023, our A Shares have been listed on the STAR Market of the Shanghai Stock Exchange. Our Directors confirmed that, and our PRC Legal Adviser is of the view that, during the Track Record Period and up to the Latest Practicable Date, there had been no instances of our material non-compliance with the applicable rules of the Shanghai Stock Exchange and other applicable PRC securities laws and regulations. To the best knowledge of our Directors having made all reasonable enquiries, there are no material matters in relation to our compliance record on the Shanghai Stock Exchange that should be brought to the attention of the Stock Exchange or potential **[REDACTED]** of the **[REDACTED]**. Based on the independent due diligence conducted by the Sole Sponsor with the assistance of the Sole Sponsor's onshore and offshore counsel teams, nothing has come to the Sole Sponsor's attention that would cause it to disagree with our Directors' confirmation with regard to the compliance records of the Company on the Shanghai Stock Exchange.

[REDACTED] STATISTICS

	Based on a maximum [REDACTED] of HKD[REDACTED] per H Share
[REDACTED] of our H Shares(1)(2)	HK$**[REDACTED]**
[REDACTED] of our Shares upon completion of the **[REDACTED]**(1)(3)	HK$**[REDACTED]**
Unaudited **[REDACTED]** adjusted consolidated net tangible assets per Share(4)(5)	HK$**[REDACTED]**

Notes:

(1) All statistics in the table are based on the assumption that the **[REDACTED]** is not exercised.

(2) The calculation of **[REDACTED]** of our H Shares is based on the assumption that **[REDACTED]** H Shares will be in **[REDACTED]** immediately upon completion of the **[REDACTED]**.

(3) The calculation of **[REDACTED]** of our Shares is based on the assumption that **[REDACTED]** H Shares will be in **[REDACTED]** immediately upon completion of the **[REDACTED]**, and 186,871,209 A Shares (including Treasury Shares) are issued and outstanding immediately upon completion of the **[REDACTED]** with an average closing price of RMB**[REDACTED]** during the **[REDACTED]** trading days of A Shares immediately preceding the Latest Practicable Date.

(4) The unaudited **[REDACTED]** adjusted consolidated net tangible assets per Share is calculated on the basis that **[REDACTED]** Shares and excluding 867,474 A Shares repurchased and 8,367 Type I Restricted Shares account as Treasury Shares (representing 133,327,968 A Shares in issue as at 31 December 2025, adding **[REDACTED]**) were in issue and after making the adjustments referred to in the section headed "Appendix II — Unaudited **[REDACTED]** Financial Information" in this document.

(5) No adjustment has been made to reflect any trading result or other transactions of the Group entered into subsequent to 31 December 2025. In particular, the unaudited **[REDACTED]** adjusted net tangible assets of the Group has not taken into account the impact of subsequent events: (i) on 9 February 2026, the Company cancelled 286 Type I Restricted Shares granted under the 2024 share incentive scheme as the applicable performance vesting conditions were not met. (ii) on 13 May 2026, the Company issued 399,603 ordinary shares as a result of the exercise of Type II Restricted Shares under 2024 share incentive scheme of the company and (iii) on 15 June 2026, the Company announced a cash dividend of RMB138,174 thousand to be distributed and the transfer of share premium into share capital for 53,140,692 ordinary shares If the impact of subsequent events had been accounted for as at 31 December 2025, the unaudited **[REDACTED]** adjusted consolidated net tangible assets per Share as of 31 December 2025 would be RMB**[REDACTED]** (equivalent to HK$**[REDACTED]**), based on an **[REDACTED]** of HK$**[REDACTED]** per Share.

DIVIDENDS

In 2023, 2024 and 2025, we paid dividends of RMB20.8 million, RMB96.5 million and RMB71.0 million, respectively, representing final dividends in respect of the preceding year. Pursuant to our Articles of Association and in accordance with the PRC Company Law (《中華人民共和國公司法》) and the No. 3 Guideline for the Supervision of Listed Companies — Cash Dividend Distribution of Listed Companies (2025 Revision) (《上市公司監管指引第3號 — 上市公司現金分紅(2025年修訂)》), we have adopted a general dividend policy, pursuant to which we may declare dividends in the form of cash dividends, stock dividends, or a combination of both, subject to applicable laws and our Articles of Association. In addition, our Board of Directors may, having regard to our funding requirements, propose interim dividends. In determining whether to declare and pay dividends, our Directors take into account, among others, the nature of the industry in which we operate, our stage of development, business model, profitability and major capital expenditure plans.

FUTURE PLANS AND USE OF [REDACTED]

Assuming that the **[REDACTED]** is not exercised and based on the maximum **[REDACTED]** of HK$**[REDACTED]** per **[REDACTED]**, we estimate that we will receive net **[REDACTED]** of approximately HK$**[REDACTED]** from the **[REDACTED]**, after deducting **[REDACTED]** and estimated expenses payable by us in connection with the **[REDACTED]**.

In line with our strategies, we intend to use the net **[REDACTED]** from the **[REDACTED]** for the purposes and in the amounts set forth below: (i) approximately **[REDACTED]**% of the net **[REDACTED]**, or HK$**[REDACTED]**, will be used to enhance our R&D and innovation capabilities. We regard independent R&D and innovation as our core development strategy, and plan to maintain a high level of R&D investment to continuously upgrade our products;(ii) approximately **[REDACTED]**% of the net **[REDACTED]**, or HK$**[REDACTED]**, will be used to further enrich our product matrix and expand downstream application scenarios; (iii) approximately **[REDACTED]**% of the net **[REDACTED]**, or HK$**[REDACTED]**, will be used to expand our overseas business network and enhance our presence in international markets; (iv) approximately **[REDACTED]**% of the net **[REDACTED]**, or HK$**[REDACTED]**, will be used to pursue strategic investments and acquisitions within the global semiconductor industry; and (v) approximately **[REDACTED]**% of the net **[REDACTED]**, or HK$**[REDACTED]**, will be used for working capital and general corporate uses.

[REDACTED]

Our **[REDACTED]** mainly include (i) **[REDACTED]** expenses, such as **[REDACTED]** fees and **[REDACTED]**, and (ii) **[REDACTED]** expenses, comprising professional fees paid to our legal advisors and Reporting Accountants for their services rendered in relation to the **[REDACTED]** and the **[REDACTED]**, and other fees and expenses. Assuming full payment of the discretionary incentive fee, the estimated total **[REDACTED]** (based on the maximum **[REDACTED]** of HK$**[REDACTED]** and assuming that the **[REDACTED]** is not exercised) for the **[REDACTED]** are approximately HK$**[REDACTED]**, accounting for approximately **[REDACTED]**% of our gross **[REDACTED]**. Among such estimated total **[REDACTED]**, we expect to pay **[REDACTED]** expenses of HK$**[REDACTED]**, professional fees for our legal advisors and Reporting Accountants of

HK$**[REDACTED]** and other fees and expenses of HK$**[REDACTED]**. An estimated amount of HK$**[REDACTED]** for our **[REDACTED]**, accounting for approximately **[REDACTED]**% of our gross **[REDACTED]**, was or is expected to be expensed through the statement of profit or loss and the remaining amount of HK$**[REDACTED]** is expected to be recognized directly as a deduction from equity upon the **[REDACTED]**. We recognized **[REDACTED]** of RMB**[REDACTED]** in our consolidated statements of profit or loss and other comprehensive income during the Track Record Period.

RECENT DEVELOPMENT AND NO MATERIAL ADVERSE CHANGE

Subsequent to the Track Record Period, we have experienced steady business growth. Our revenue increased by 17.6% in the three months ended March 31, 2026 compared to the same period in 2025, according to our management account. The sales volume of our smart video chips increased by 39.9% in the three months ended March 31, 2026 compared to the same period in 2025, and the sales volume of our interconnect chips increased by 45.1% in the three months ended March 31, 2026 as compared to the same period in 2025. The growth of our revenue and sales volume is attributable to our continuous product iterations and the wide market acceptance of our new products with enhanced performance.

Moreover, we have cooperated with a leading global technology company on the development of mixed reality glasses. Relevant products are currently in the trial production stage, and we have shipped multiple batches of products for customer's examination and verification. Subject to the customer's commercialization schedule, mass production is expected to commence in the second half of 2026.

Our Directors have confirmed that, up to the date of this document, there has been no material adverse change in our financial or trading position or prospects since December 31, 2025, being the end date of our latest consolidated financial statements, and there has been no event since December 31, 2025 that would materially affect the information shown in the Accountants' Report set out in Appendix I to this document.